

## ABSTRACT OF THE DISCLOSURE

### **MEMS MICROPHONE PACKAGE HAVING SOUND HOLE IN PCB**

5        Provided is a MEMS microphone package having a sound hole in  
a PCB, which can ground-connect a metal case to a main board  
using an assembly process including bending and clamping an end  
of the case. The MEMS microphone package includes a tetragonal  
container-shaped metal case having an open-side to insert  
10 components into an inner space, and a chamfered end on the open-  
side to easily perform a curling operation, a printed circuit  
board (PCB) substrate to which a MEMS microphone chip and an  
application specific integrated circuit (ASIC) chip are mounted,  
the PCB substrate being inserted into the metal case and having a  
15 sound hole for introducing an external sound, and a support  
configured to support the PCB substrate in the curling operation  
and define a space between the metal case and the PCB substrate.

[Figure 3]

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